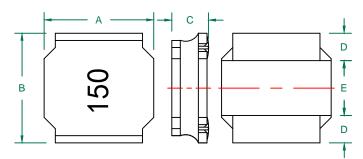
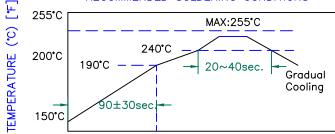
TYS6045150M-10

PHYSICAL DIMENSIONS:

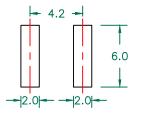
Α	6.00	±	0.30
В	6.00	±	0.30
С	4.50	+	0.20 0.30
D	1.80	±	0.30
F	2.40	+	0.30

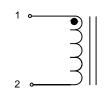


RECOMMENDED SOLDERING CONDITIONS



LAND PATTERNS FOR REFLOW SOLDERING

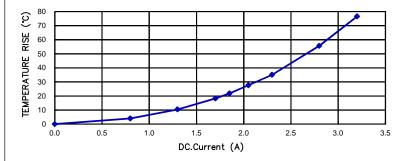




ELECTRICAL SPECIFICATION

	Min	Nom	Max
INDUCTANCE (uH) L @ 100 KHz/1V ± 20%	12.0	15.0	18.0
DCR (Ω)		0.068	0.0884

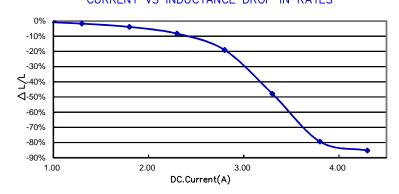
CHARACTERISTICS OF TEMPERATURE RISE





Saturation Current(A)	2.50
SRF (MHz)	12
Temperature Rise Current (A)	2.05

CURRENT VS INDUCTANCE DROP IN RATES



NOTES:

- 1.OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
- 2.STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): -10°C TO +40°C AND RH 70% (MAX.)
- 3.UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
 A. AMBIENT TEMPERATURE: 201150.
- B. RELATIVE HUMIDITY: 65%±20%.
- 4.SATURATION CURRENT IS THE DC CURRENT AT WHICH THE INDUCTANCE DROPS OFF APPROXIMATELY 30% FROM ITS VALUE WITHOUT CURRENT.(AMBIENT TEMPERATURE 25±5°C)
- 5. TEMPERATURE RISE CURRENT (IRMS):

DC CURRENT THAT CAUSES THE TEMPERATURE RISE (△T ≤40°C) FROM 25°C AMBIENT.

DIMENSIONS ARE IN mm .				This print is the property of Laird						
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				rights to design or invention are reserved.						
D	CHANGE DIMENSIONS C/D/E	08/18/16	QIU	PROJECT/PART NUMBER:	- 1		PART TO		DRAWN BY:	
С	CHANGE TEMP FROM -25℃~+125℃	12/24/12		TYS6045150M-10		D		WER CTOR	QIU	
В	ADD CURVE	05/08/12	QIU	DATE: 02/06/12	SCALE	3 N.		SHEET:		
Α	ORIGINAL DRAFT	02/06/12	QIU		TOOL	NTS				
REV	DESCRIPTION	DATE	INT					1	of 1	